

LAYER STACK-UP - ALL DIMENSIONS IN INCHES

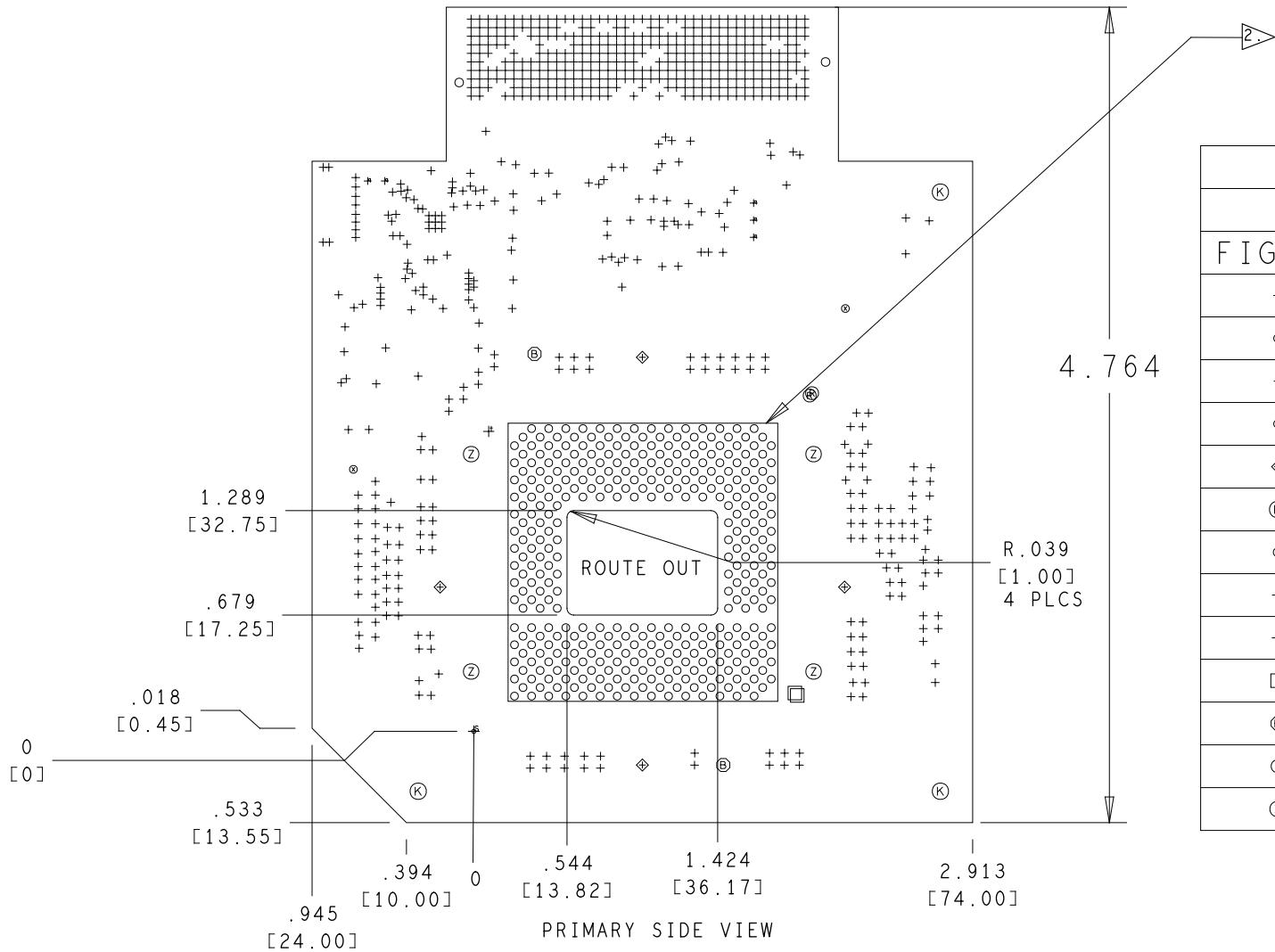
		50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	90ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (OZ)	TRACE WIDTH	TRACE WIDTH / SPACE	TRACE WIDTH / SPACE
LAYER 1 - PRIMARY SIDE - SIGNAL	HALF+PLATING	0.0048		
LAYER 2 - GROUND PLANE	H			
LAYER 3 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 4 - GROUND PLANE	H			
LAYER 5 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 6 - GROUND PLANE	H			
LAYER 7 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 8 - GROUND PLANE	H			
LAYER 9 - SPLIT POWER PLANE	H			
LAYER 10 -SPLIT POWER PLANE	H			
LAYER 11 -GROUND PLANE	H			
LAYER 12 -SIGNAL	H	0.005		0.004/ 0.005
LAYER 13 -GROUND PLANE	H			
LAYER 14- SIGNAL	H	0.005		0.004/ 0.005
LAYER 15 -GROUND PLANE	H			
LAYER 16 -SIGNAL	H	0.005		0.004/ 0.005
LAYER 17 -GROUND PLANE	H			
LAYER 18- SECONDARY SIDE - SIGNAL	HALF+PLATING	0.0048		

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010". DIMENSIONS ARE FOR REFERENCE ONLY - USE ARTWORK FOR ACCURATE MEASUREMENT OF THE BOARD OUTLINE.
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE HITACHI MCL-HE-679G OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL-REGISTERED MATERIAL ID NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .095 INCHES +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- NON-PLATED THROUGH SLOTS INDICATED WITH MULTIPLE DRILL HITS SHOULD BE FINISHED AS SMOOTH WALL BY VENDOR.
- FABRICATOR SHOULD REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.

PROCESS NOTES:

- EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 150 MICROINCHES THK MIN GOLD 5-15 MICROINCHES THK MIN.
- PLATE ALL THE PADS OF U1 ON THE BOTTOM SIDE WITH A MINIMUM OF 35 AND MAXIMUM 50 MICRO-INCHES OF ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 100 MICRO-INCHES OF ELECTROLYTIC NICKEL.
- APPLY LPI OR LDI SOLDERMASK, COLOR: BLUE. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
- FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
+	10.0	+3.0/-10.0	PLATED	681
o	12.0	+3.0/-12.0	PLATED	355
+	40.0	+2.0/-2.0	PLATED	5
o	63.0	+3.0/-3.0	PLATED	2
◇	138.0	+3.0/-3.0	PLATED	4
K	157.0	+3.0/-3.0	PLATED	3
o	50.0	+3.0/-3.0	NON-PLATED	2
+	59.0	+2.0/-2.0	NON-PLATED	1
+	67.0	+2.0/-2.0	NON-PLATED	1
□	79.0	+2.0/-2.0	NON-PLATED	2
B	82.0	+3.0/-3.0	NON-PLATED	2
B	96.0	+2.0/-2.0	NON-PLATED	2
Z	157.0	+3.0/-3.0	NON-PLATED	4

TEXAS INSTRUMENTS

BOARD NAME:		DESCRIPTION: DRILL DRAWING	
PROJECT #: DLP083		DATE: 28 FEB 2023	REVISION: REV D